

**RELIABILITY MONITOR REPORT
FOR**

TSOC Package

Dallas Semiconductor

**4401 South Beltwood Parkway
Dallas, TX 75244-3292**

**This Report was prepared by
Dallas Semiconductor Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE		
Carsem	6	TSOC	OSEP	6 TSOC

The calculated failure rate for this assembly is:

The parameters used to calculate this failure rate are as follows:

Cf: 60% **Ea: 0.7** **B: 0** **Tu: 25 °C** **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 10/1/03 and 9/30/04 .

Assembly Information:

Package Type: TSOC 150 mil
 Flammability: UL 94-V0
 Moisture Sensitivity
 (JEDEC J-STD20A) Level 1
 Date Code Range: 0410 to 0410

PRECONDITIONING LEVEL 1

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
ULTRASOUND	0410	DS2502	J-STD-020		4	0	
STORAGE LIFE	0410	DS2502	125C	24 HRS	151		
MOISTURE SOAK			85 C/85% R.H.	168 HRS	151		
CONVECTION REFLOW			235C +5/-0C	3 PASS	151	0	
PRECONDITION U/S	0410	DS2502	J-STD-020		4	0	
Total:						0	

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE	0410	DS2502	-55C TO 125C	1000 CYS	77	0	
Total:						0	

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
AUTOCLAVE	0410	DS2502	121C, 2 ATM STEAM, UNBIASED	168 HRS	70	0	
Total:						0	